PRODUCT / PROCESS CHANGE NOTIFICATION

1. PCN basic data

1.1 Company	STMicroelectronics International N.V
1.2 PCN No.	POWER AND DISCRETES/25/15852
1.3 Title of PCN	Conversion of DPAK package at ST plant in China to ECOPACK®2 grade (Green Molding Compound) for Non-automotive STPS/STTHxxxB-TR products
1.4 Product Category	Non-automotive STPS/STTHxxxB-TR products
1.5 Issue date	2025-11-10

2. PCN Team

2.1 Contact supplier	
2.1.1 Name	ROBERTSON HEATHER
2.1.2 Phone	+1 8475853058
2.1.3 Email	heather.robertson@st.com
2.2 Change responsibility	
2.2.1 Product Manager	Stephane CHAMARD
2.1.2 Marketing Manager	Philippe LEGER
2.1.3 Quality Manager	Julien MICHELON

3. Change

3.1 Category	3.2 Type of change	3.3 Manufacturing Location
Materials	Direct Material: Mold compound - Chemistry (raw material)	ST Shenzhen - China

4. Description of change

	Old	New
4.1 Description	Non-Green Molding compound ECOPACK®1 Mold compound MG2 (Material Group II)	Green Molding compound ECOPACK®2 Mold compound MG1 (Material Group I)
4.2 Anticipated Impact on form,fit, function, quality, reliability or processability?	No	

5. Reason / motivation for change

5.1 Motivation	To comply with so-called “Halogen-free” requirements (ST ECOPACK®2) and Material Group I DFD division strategy.
5.2 Customer Benefit	QUALITY IMPROVEMENT

6. Marking of parts / traceability of change

6.1 Description	Traceability of the change will be ensured by Finished Good/Type and Category print on carton labels. ECOPACK®2 component will be marked with the letter “G” on package body.

7. Timing / schedule

7.1 Date of qualification results	2025-10-30
7.2 Intended start of delivery	2026-02-15
7.3 Qualification sample available?	Upon Request

8. Qualification / Validation

8.1 Description	15852 25028QRP.pdf		
8.2 Qualification report and qualification results	Available (see attachment)	**Issue Date**	2025-11-10

9. Attachments (additional documentations)

15852 Public product.pdf
15852 GMC DPAK Non auto.pdf
15852 25028QRP.pdf

10. Affected parts

10. 1 Current		10.2 New (if applicable)
10.1.1 Customer Part No	**10.1.2 Supplier Part No**	**10.1.2 Supplier Part No**
	STPS10170CB-TR	
STPS1045B	STPS1045B	
STPS1045B-TR	STPS1045B-TR	
STPS15H100CB	STPS15H100CB	
STPS15H100CB-TR	STPS15H100CB-TR	
STPS15L30CB-TR	STPS15L30CB-TR	
STPS15L45CB	STPS15L45CB	
STPS15L45CB-TR	STPS15L45CB-TR	
STPS15L60CB	STPS15L60CB	
STPS15L60CB-TR	STPS15L60CB-TR	
	STPS16170CB-TR	
	STPS4S200B-TR	
STPS5H100B	STPS5H100B	
STPS5H100B-TR	STPS5H100B-TR	
STPS5L25B-TR	STPS5L25B-TR	
STPS640CB-TR	STPS640CB-TR	
STPS8L30B-TR	STPS8L30B-TR	
STTH1002CB	STTH1002CB	
STTH1002CB-TR	STTH1002CB-TR	
	STTH1003SB-TR	
	STTH4R02B-TR	
	STTH506B-TR	
STTH5L06B-TR	STTH5L06B-TR	
STTH5R06B	STTH5R06B	
STTH5R06B-TR	STTH5R06B-TR	
	STTH802B-TR	
STTH802CB-TR	STTH802CB-TR	

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Public Products List

Publict Products are off the shelf products. They are not dedicated to specific customers, they are available through ST Sales team, or Distributors, and visible on ST.com

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to ECOPACK®2 grade (Green Molding Compound)
for Non-automotive STPS/STTHxxxB-TR products
PCN Reference : POWER AND DISCRETES/25/15852

Subject : Public Products List

Dear Customer,

Please find below the Standard Public Products List impacted by the change.

STPS10170CB-TR	STTH5R06B-TR	STPS4S200B-TR
STPS16170CB-TR	STPS5H100B	STTH1002CB
STPS15L60CB-TR	STPS640CB-TR	STPS15L60CB
STPS8L30B-TR	STPS5H100B-TR	STTH802CB-TR
STPS5L25B-TR	STTH802B-TR	STPS15L45CB
STTH4R02B-TR	STPS20120CB-TR	STTH506B-TR
STPS15H100CB	STPS15L30CB-TR	STPS15L45CB-TR
STTH5R06B	STTH5L06B-TR	STPS15H100CB-TR
STTH1003SB-TR	STTH1002CB-TR	STPS1045B
STPS1045B-TR		

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